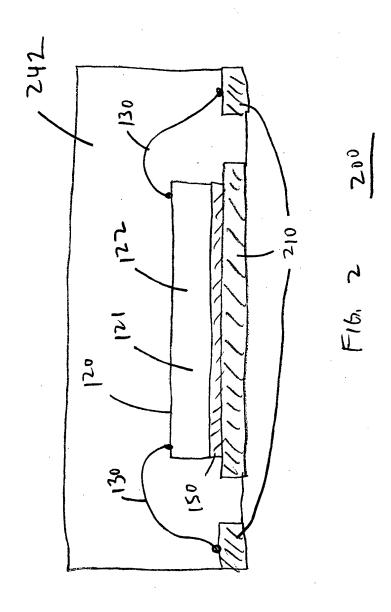


F16, - 100

1

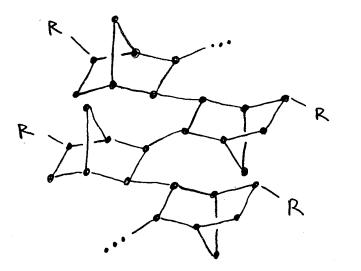


J



F16. 3

3.00



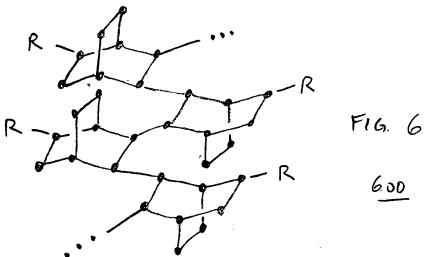
F16. 4

400



F16. 5

500





## <u>700</u>

Providing a semiconductor substrate
<u> </u>
Providing a lead frame
<b>↓</b>
Mounting the semiconductor substrate over the lead frame
<b>.</b>
Electrically coupling a device in the semiconductor substrate to the lead frame
<b>↓</b>
Mixing a catalyst with monomer of an optically transparent cycloaliphatic polymer to form a packaging material
<b>↓</b>
Filtering the packaging material
<b>↓</b>
Applying the packaging material over the semiconductor substrate and the lead frame
Curing the packaging material